

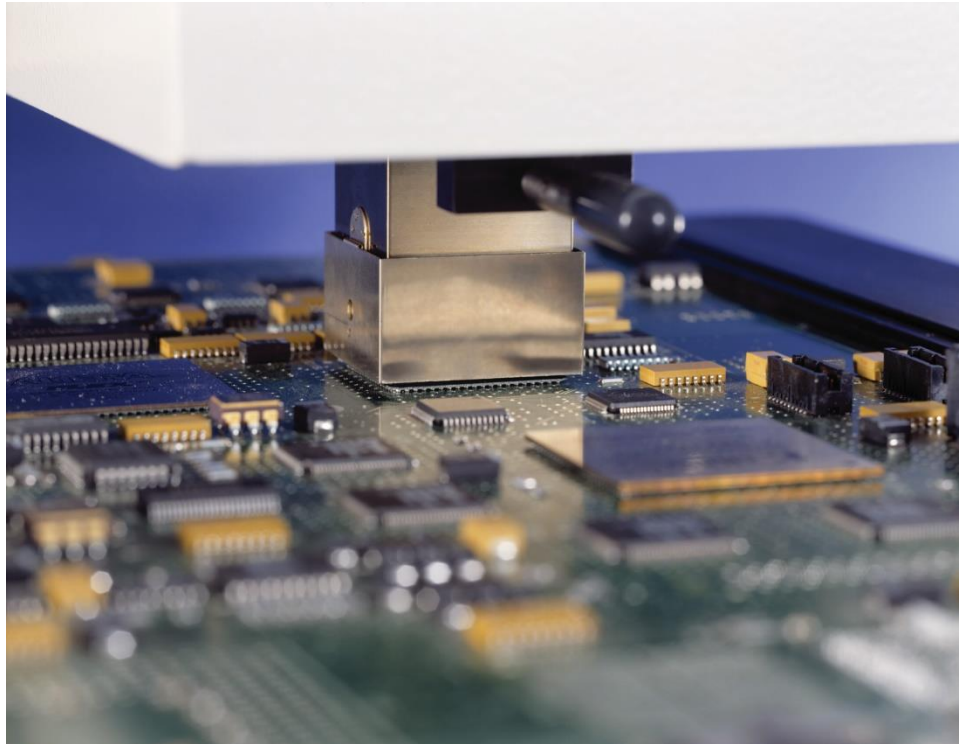


## **FOR IMMEDIATE RELEASE**

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## **PACE & Cumberland Electronics to Present BGA/Area Array Component Rework Workshops in Philadelphia & Baltimore in September**



Vass, NC – Aug 29, 2019 – PACE Worldwide and Cumberland Electronics have teamed up to host two separate Technical Workshops on “Non-Destructive BGA/Area Array Component Rework” on September 10th at ACI Technologies in Philadelphia PA, and on September 12<sup>th</sup> at the PACENTER Training Center in Elkridge MD. Both Workshops

are scheduled from 9 am – 12 noon. Refreshments/snacks will be served before each presentation.

In the past 20 years, such mundane operations as soldering, desoldering and component replacement have become complicated by extreme micro-miniaturization, the use of lead-free solders, new thermally challenging pc boards, heat-sinking bottom terminated components and intricate component packages that are difficult to rework or install. One area that presents unique challenges is BGA/area array rework. Modern boards that use these components are more technically demanding than ever, requiring skilled operators who are highly competent at accomplishing delicate, intricate soldering and rework tasks. Unfortunately, many operators will cause more damage to the assembly or components due to his/her rework actions. As a result, many manufacturers struggle to repair or rework boards, opting to throw away lower value boards or hire outside contractors to perform the more difficult repairs.

This Workshop will review current techniques and procedures for performing highly reliable, high-quality rework and repair on some of the more difficult BGA packages and will include live demonstrations of PACE's TF1800 BGA Rework System. The presentation will address typical BGA/area array components, heating technologies (convection and infrared), the importance of bottom side preheating, flux application, solder paste stenciling, device alignment methods and thermal profiling techniques, followed by a live demonstration of BGA rework. Workshop participants are encouraged to bring a sample pcb for hands-on BGA removal or installation using the TF1800. In addition, a short demonstration on cleaning circuit boards at the lowest possible cost will be presented by MicroCare, an industry leader in critical cleaning products.

The Technical Workshop is free, but registration is required:

Sept 10<sup>th</sup> at ACI Philadelphia 9am-12pm: [www.ce3s.com/events-1/bga-smd-component-technical-workshop-philadelphia](http://www.ce3s.com/events-1/bga-smd-component-technical-workshop-philadelphia)

Sept 12<sup>th</sup> at PACENTER Training Center, Elkridge, MD 9am-12pm:

[www.ce3s.com/events-1/bga-smd-component-technical-workshop-maryland](http://www.ce3s.com/events-1/bga-smd-component-technical-workshop-maryland)

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### **About PACE®**

PACE Worldwide has been providing the most innovative, cost-effective solutions in hands-on soldering, rework and repair of advanced electronics to companies and government around the globe for almost 60 years. Since the dawn of the modern electronics industry, PACE has played a key role in the development of groundbreaking products, training films, curricula, materials and electronic assembly standards, including several soldering, surface mount and thru-hole rework videos co-produced with the IPC and industry.

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